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(54) SEMICONDUCTOR PACKAGE AND MANUFACTURING METHOD THEREOF

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(57)**ABSTRACT**

A semiconductor package includes a substrate, a first insulation layer, a conductive pad, a second insulation layer and a conductive trace. The first insulation layer is formed on the substrate and having a first through hole. The conductive pad is formed on the substrate through the first through hole. The second insulation layer has a first surface and a second through hole, wherein the second through hole extends to the conductive pad from the first surface. The conductive trace has a second surface and is connected to the conductive pad through the second through hole. The entire of the first surface is in the same level, and the entire of the second surface is in the same level.

